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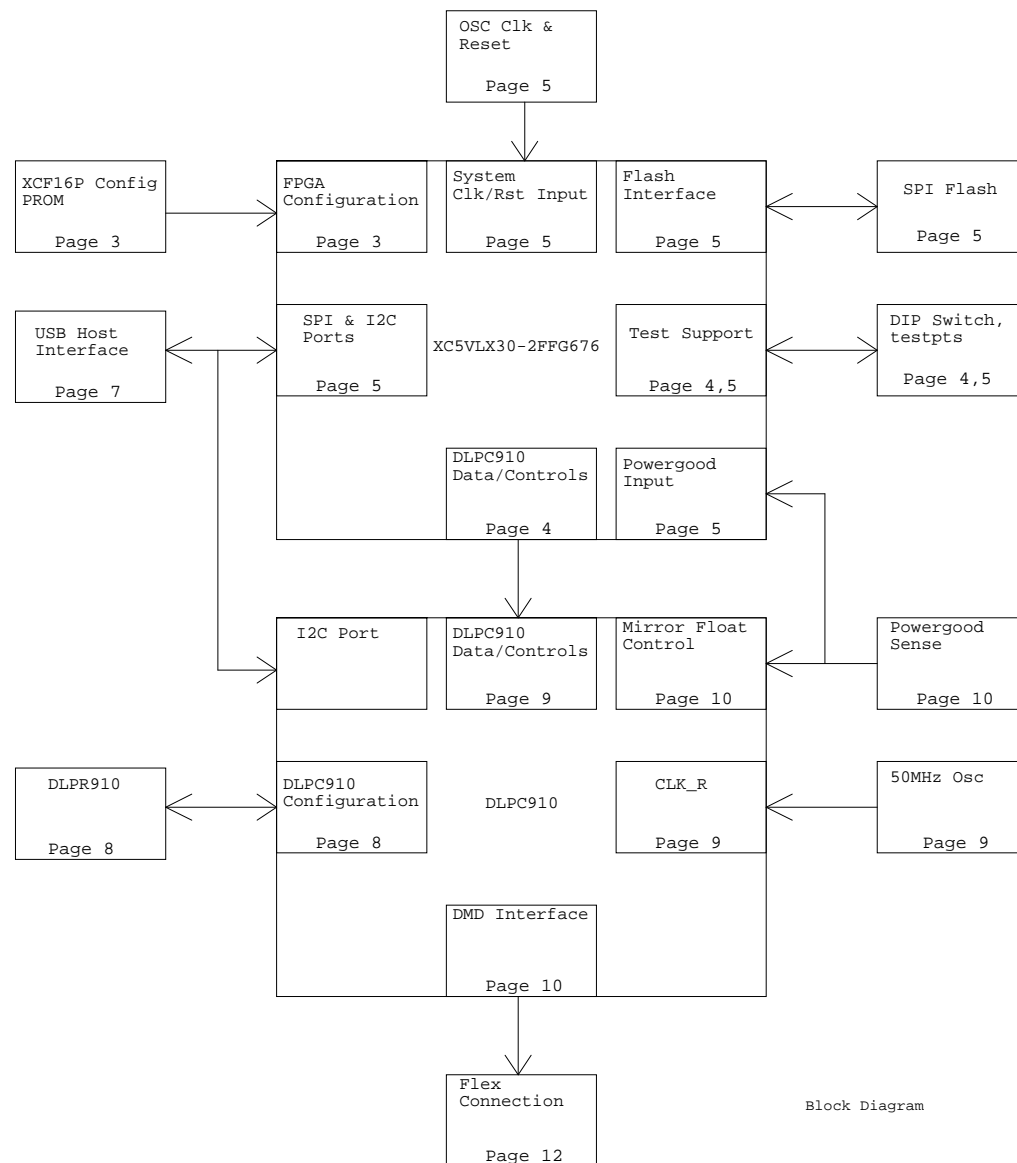
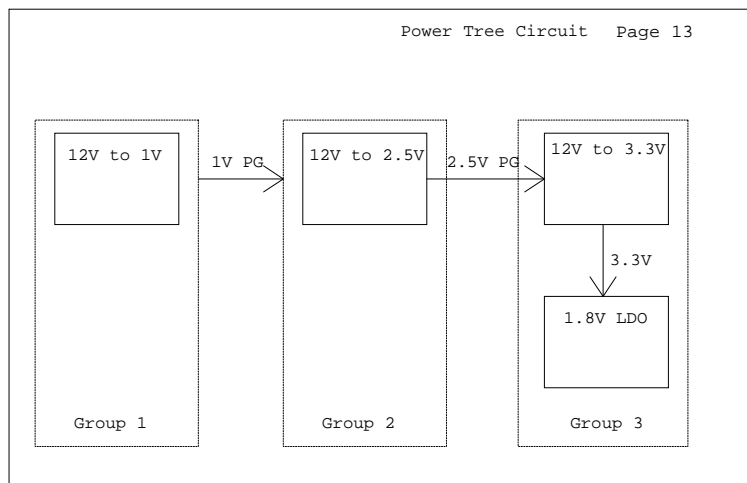
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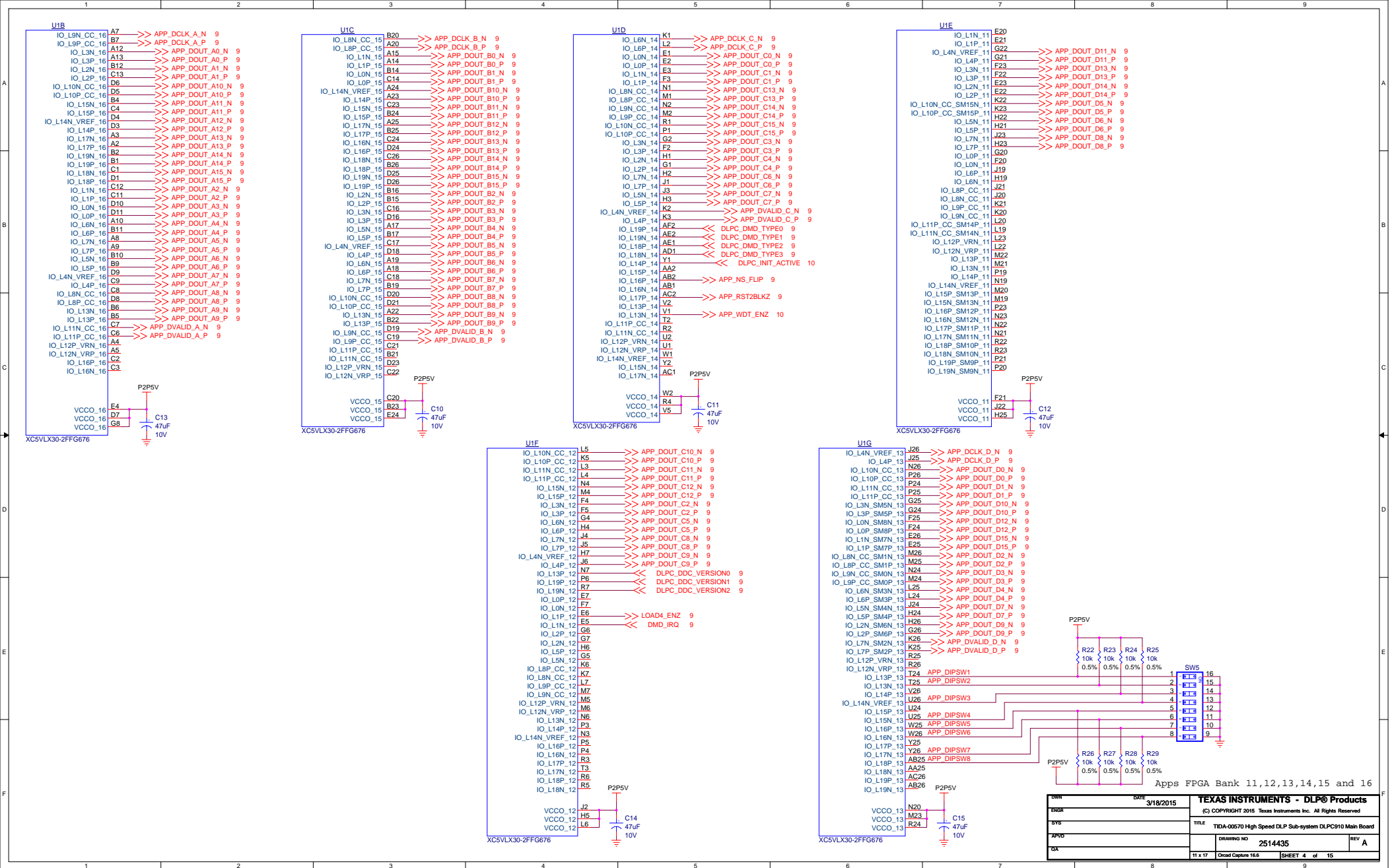
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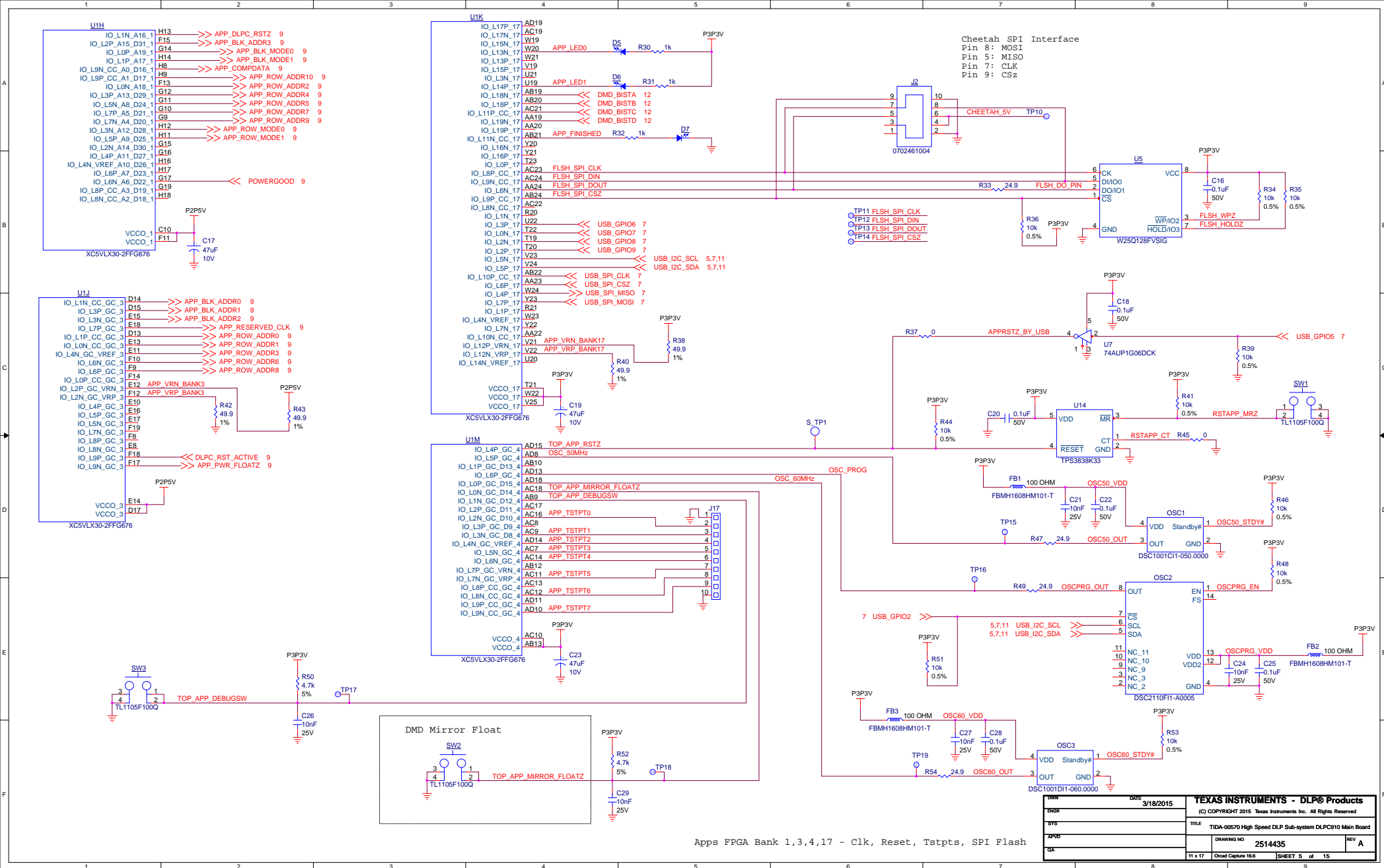
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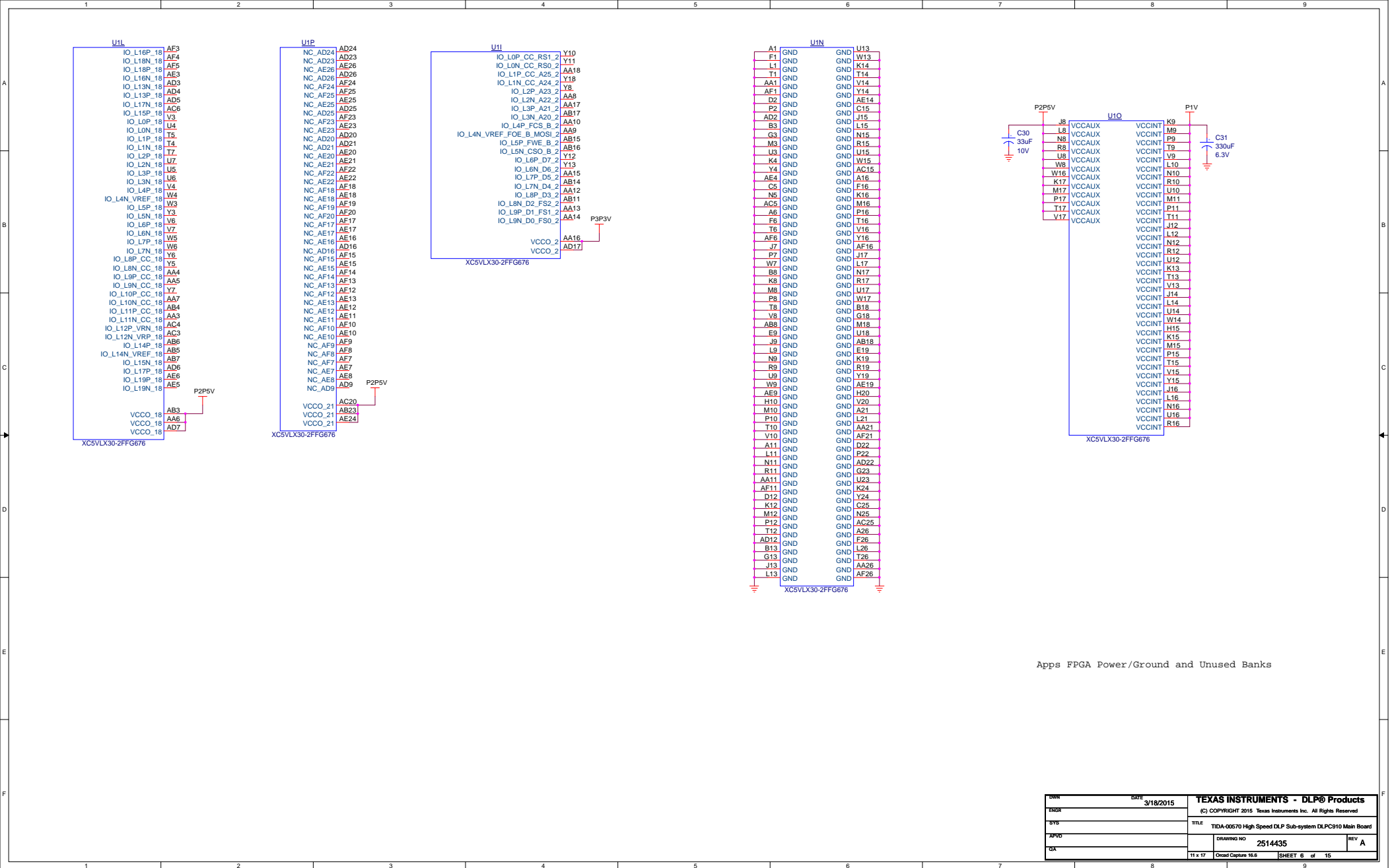
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APVD		DRAWING NO		2514435		REV
QA		11 x 17		Orcad Capture 16.6		SHEET 1 of 15

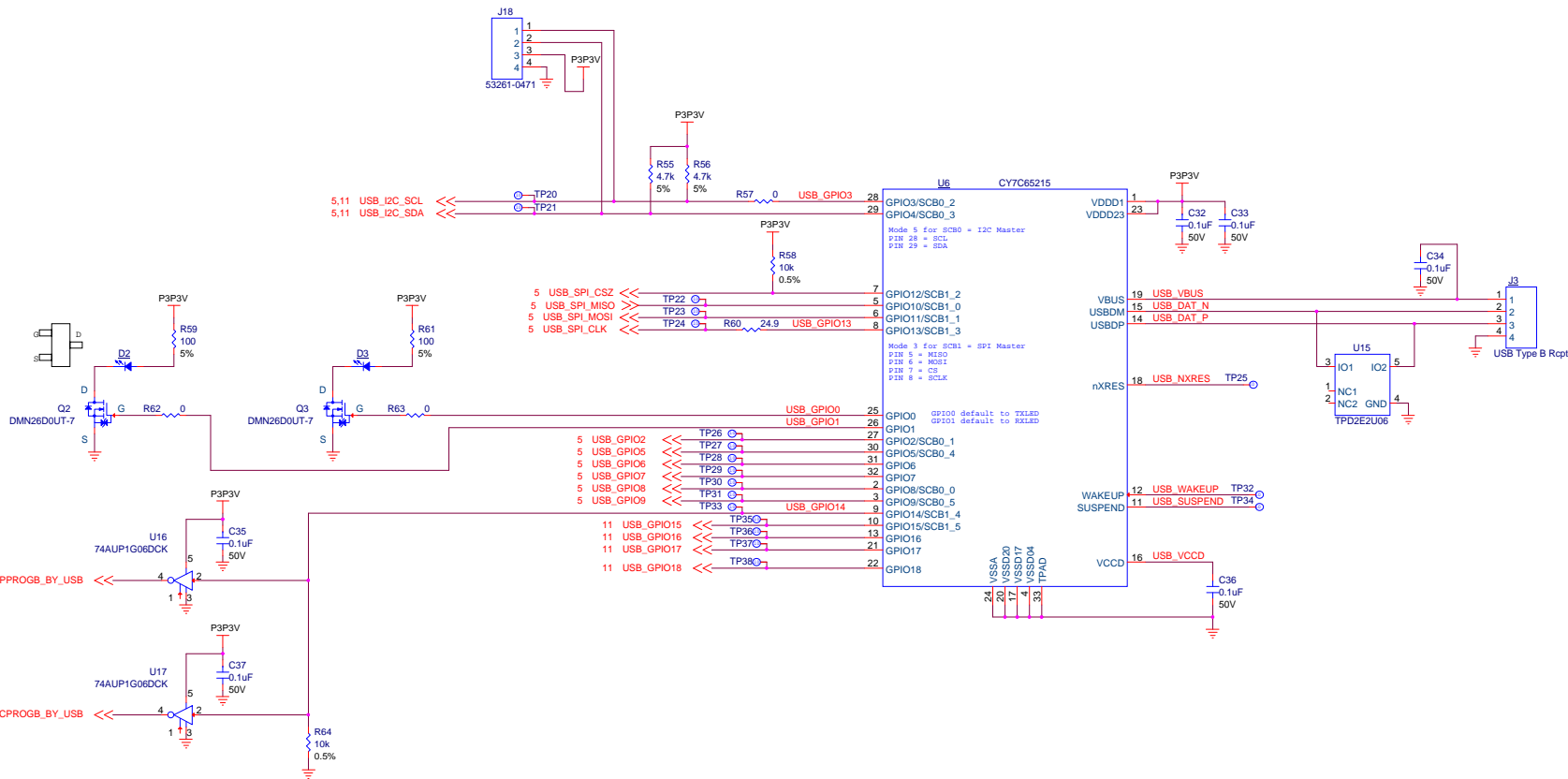


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BYS	TITLE TIDA-00570 High Speed DLP Sub-system DLPC910 Main Board				
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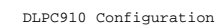




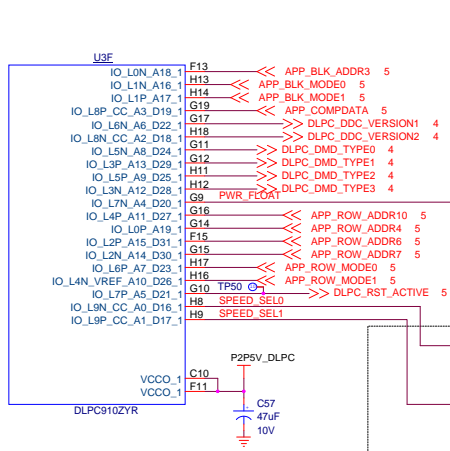
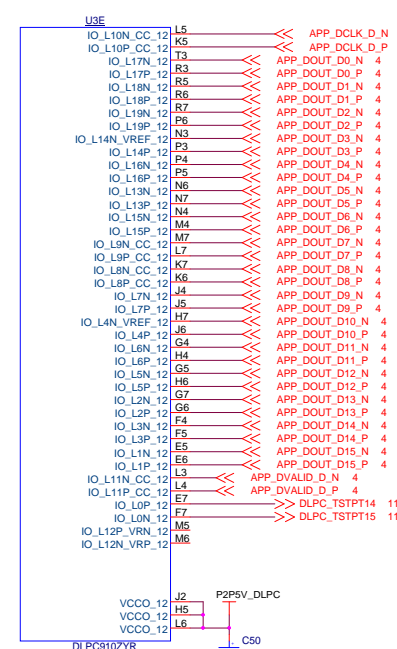
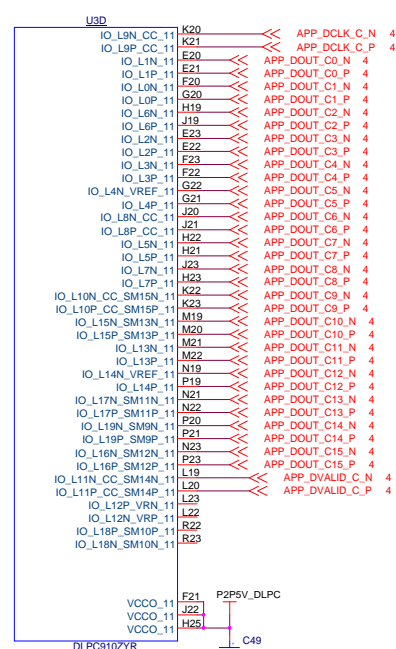
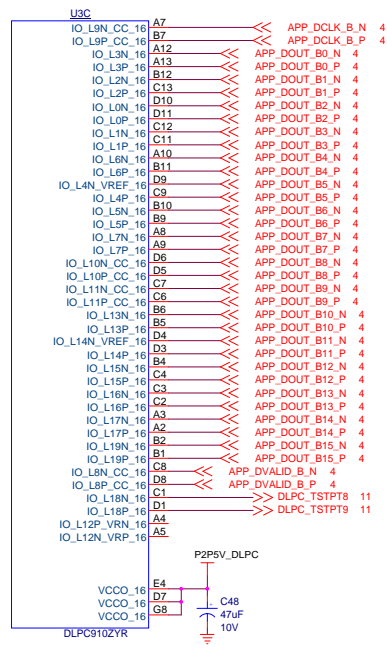
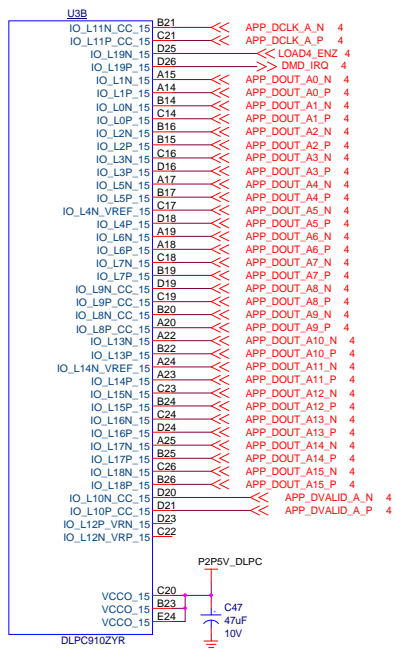


USB Interface

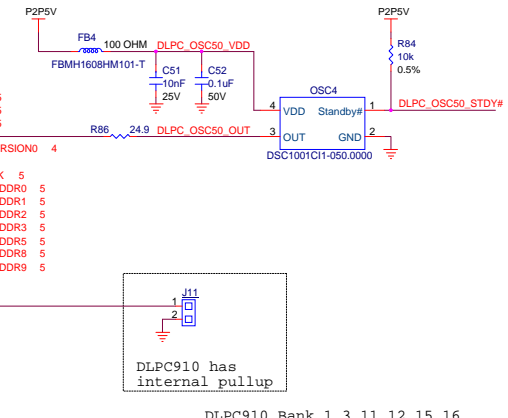
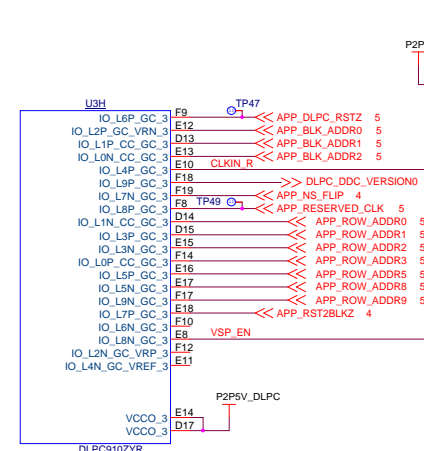
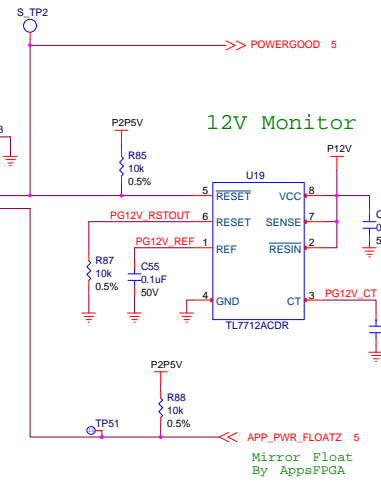
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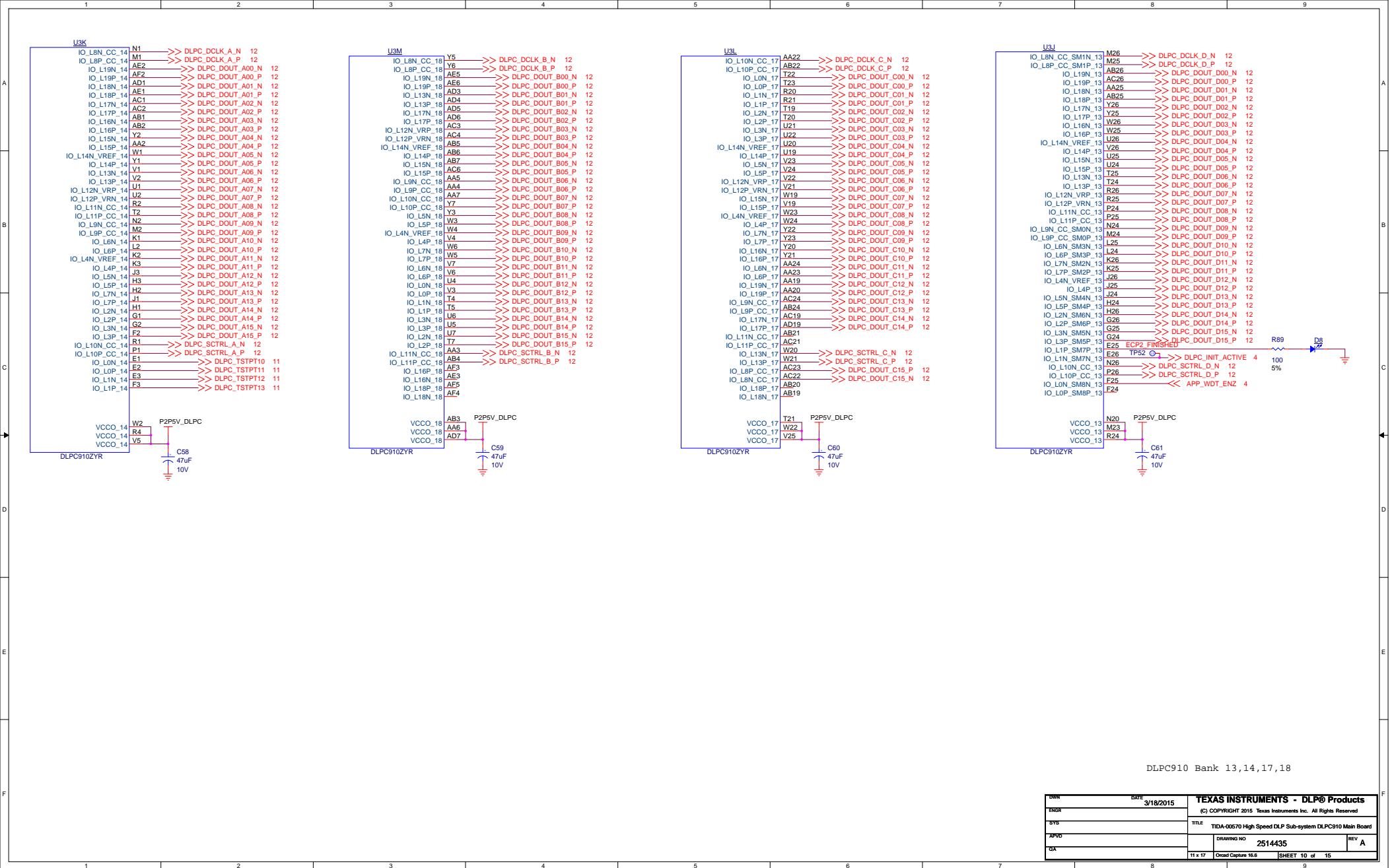
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TSYS		TITLE	TIDA-00570 High Speed DLP Sub-system DLPC3010 Main Board	
APCD		DRAWING NO	2514435	REV A
QA		11 x 17	Onset Capture 16.8	SHEET 8 of 15

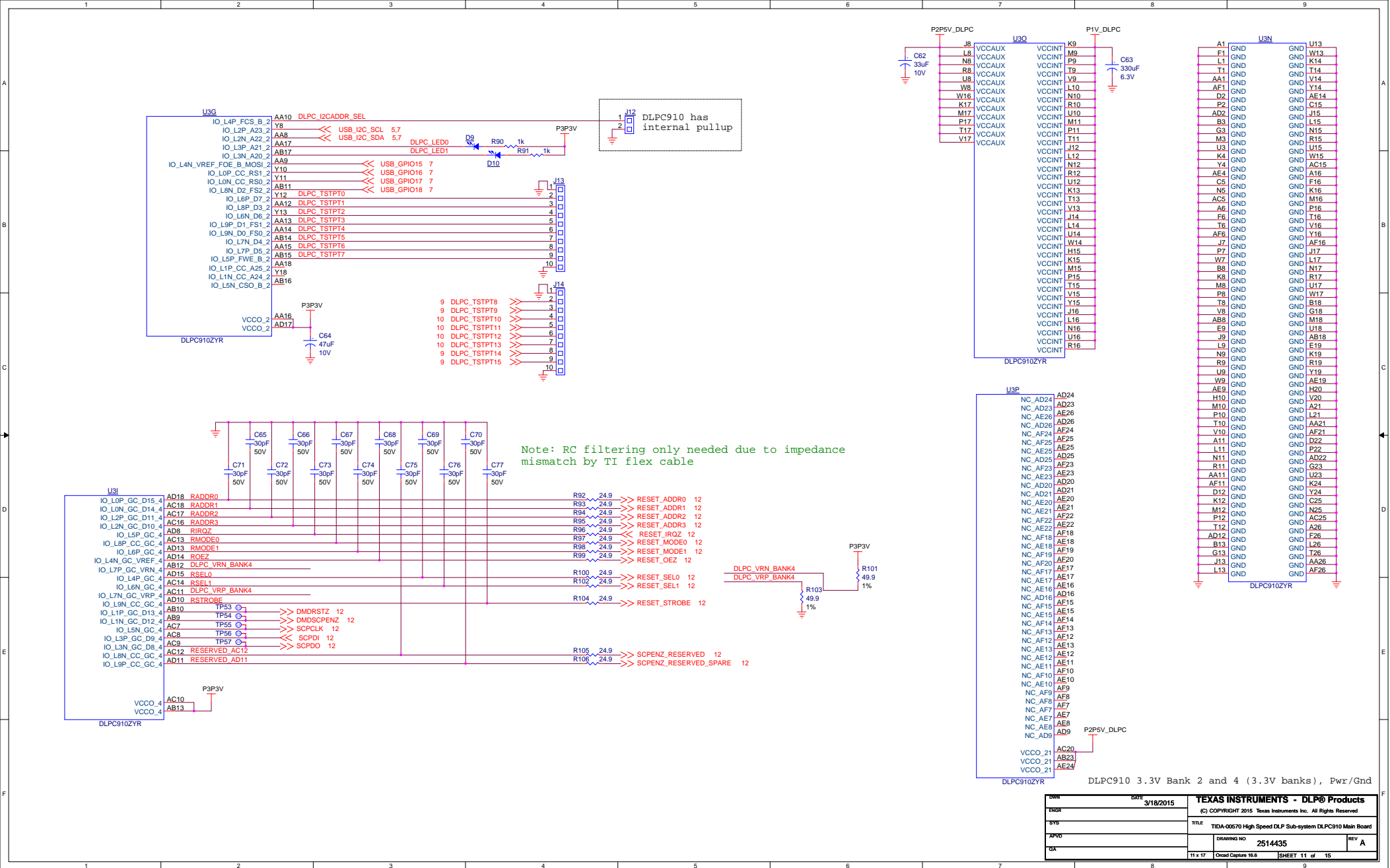


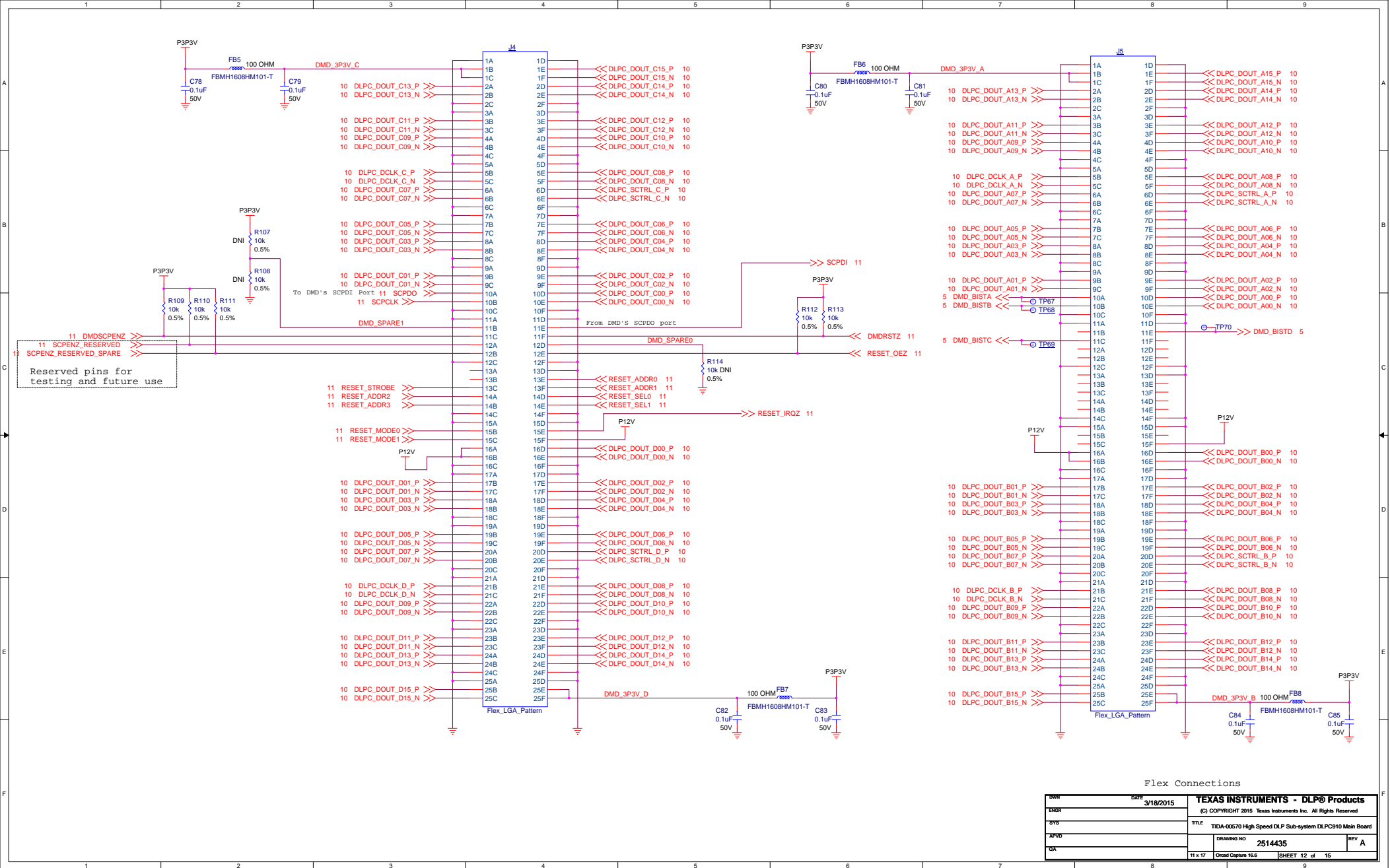
DLPC910 has internal pullup



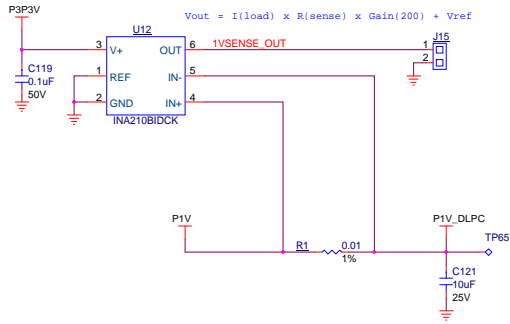
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APVD	DRAWING NO	2514435	REV A
DA	11 x 17	Sheet Capture 18.6	SHEET 9 of 15



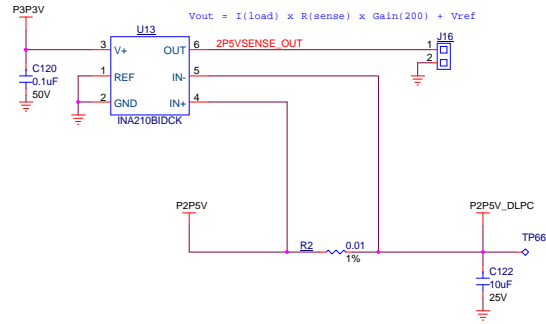




Place U12 close to R1



Place U13 close to R2



Current Sensing for DLPC910

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APVD		DRAWING NO	2514435	REV A
QA		11 x 17	Onsd Capture 18.8	SHEET 14 of 15

Revisions

Rev. A : Initial Release

REVISION NOTES

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QA					DRAWING NO		REV			
					2514435	A				
					T1 x 17	Sheet Capture 18.6	SHEET 15 of 15			